

## **FJX3001R**

### Switching Application (Bias Resistor Built In)

- Switching circuit, Inverter, Interface circuit, Driver Circuit
- Built in bias Resistor (R1=4.7KΩ, R2=4.7KΩ) WWW.DZS
- Complement to FJX4001R

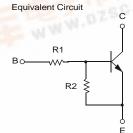


SOT-323

1. Base 2. Emitter 3. Collector

Marking





## **NPN Epitaxial Silicon Transistor**

### Absolute Maximum Ratings Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	50	V
V <sub>CEO</sub>	Collector-Emitter Voltage	50	V
V <sub>EBO</sub>	Emitter-Base Voltage	10	V
I <sub>C</sub>	Collector Current	100	mA
Pc	Collector Power Dissipation	200	mW
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-55 ~ 150	°C

## Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_{C}=10\mu A, I_{E}=0$	50			V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> =100μA, I <sub>B</sub> =0	50			V
I <sub>CBO</sub>	Collector Cut-off Current	V <sub>CB</sub> =40V, I <sub>E</sub> =0		E.	0.1	μΑ
h <sub>FE</sub>	DC Current Gain	V <sub>CE</sub> =5V, I <sub>C</sub> =10mA	20	W.W.		
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> =10mA, I <sub>B</sub> =0.5mA			0.3	V
f <sub>T</sub>	Current Gain Bandwidth Product	V <sub>CE</sub> =10V, I <sub>C</sub> =5mA		250		MHz
C <sub>ob</sub>	Output Capacitance	V <sub>CB</sub> =10V, I <sub>E</sub> =0 f=1.0MHz		3.7		pF
V <sub>I</sub> (off)	Input Off Voltage	$V_{CE}=5V, I_{C}=100\mu A$	0.5			V
V <sub>I</sub> (on)	Input On Voltage	$V_{CE}$ =0.3V, $I_{C}$ =20mA			3	V
R <sub>1</sub>	Input Resistor		3.2	4.7	6.2	ΚΩ
R <sub>1</sub> /R <sub>2</sub>	Resistor Ratio		0.9	1	1.1	

## **Typical Characteristics**

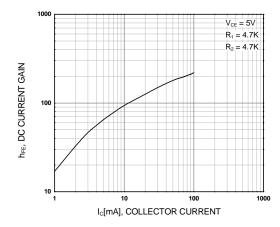


Figure 1. DC current Gain

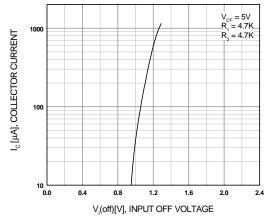


Figure 3. Input Off Voltage

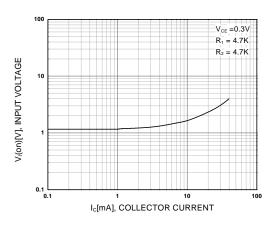


Figure 2. Input On Voltage

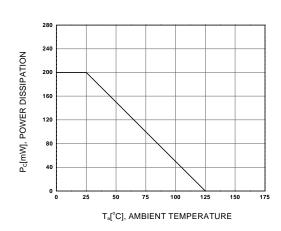
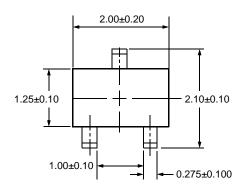


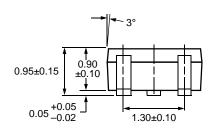
Figure 4. Power Derating

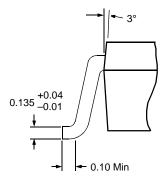
Rev. A2, August 2002

# **Package Dimensions**

# SOT-323







Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench <sup>®</sup>	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	$I^2C^{TM}$	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board.	. Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franc	hise™	OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	$VCX^{TM}$
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